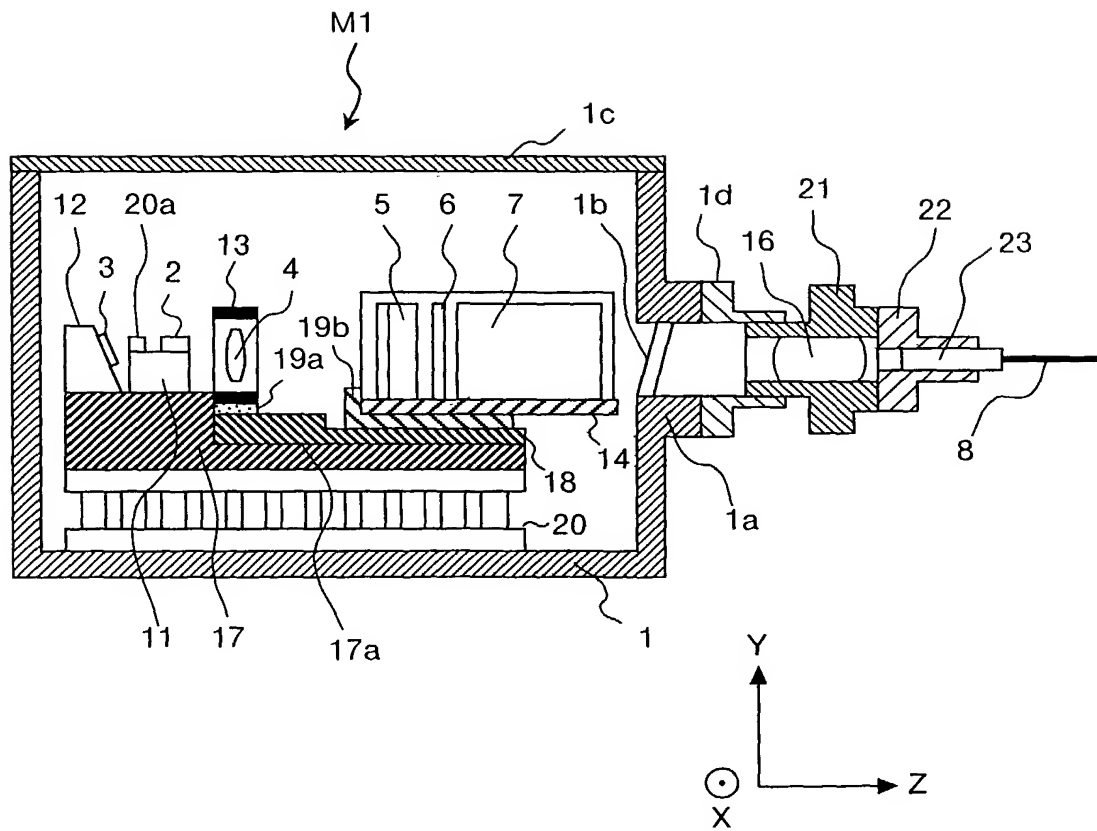


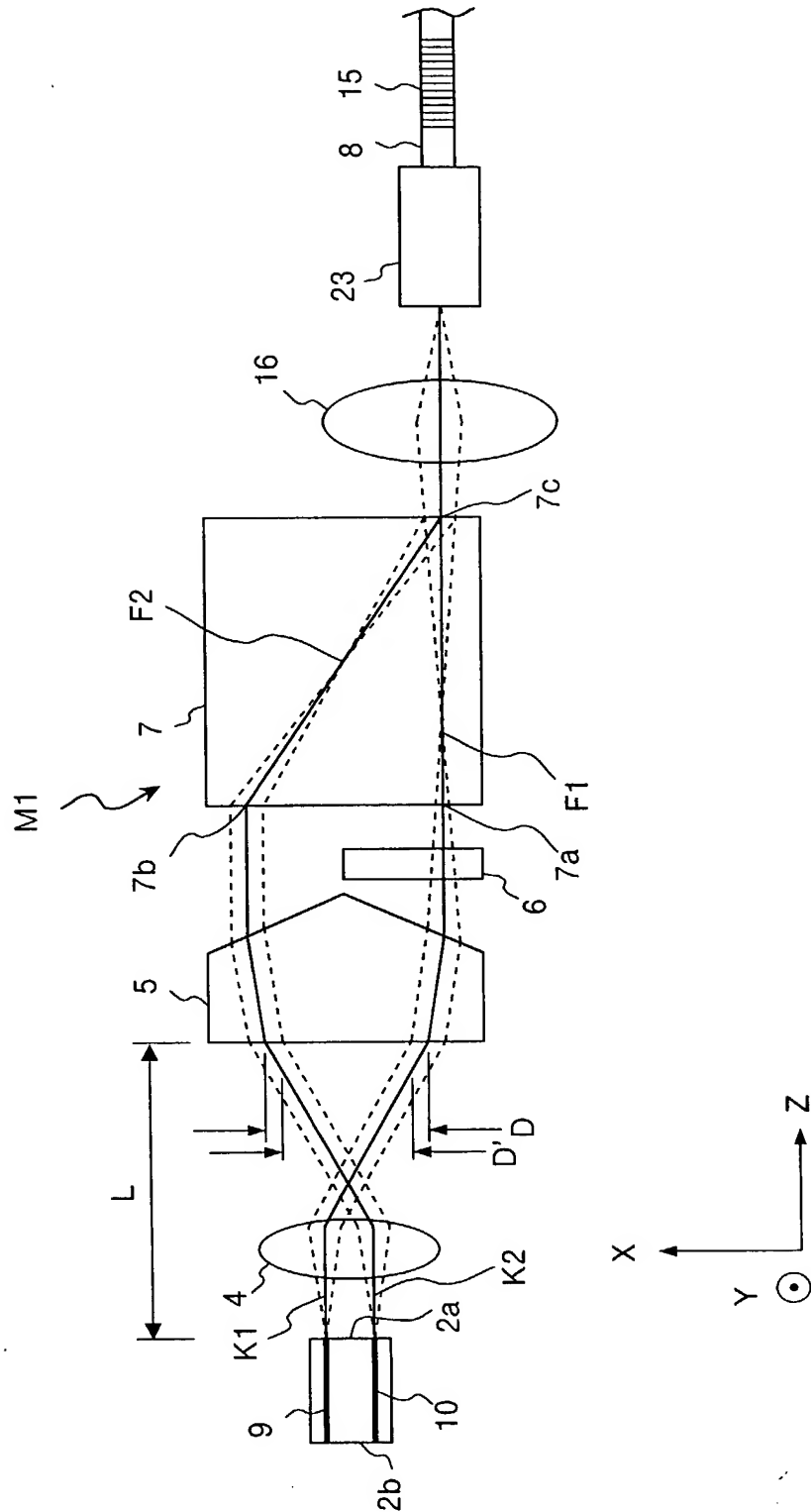
1/18

FIG.1



2/18

FIG.2



3/18

FIG.3A

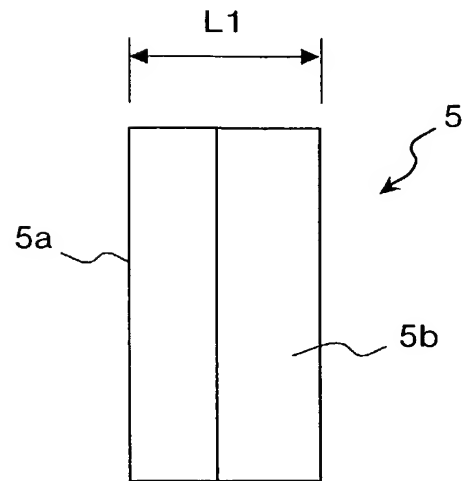
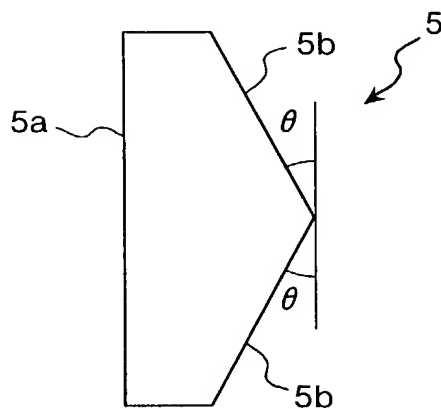


FIG.3B



4/18

FIG.4A

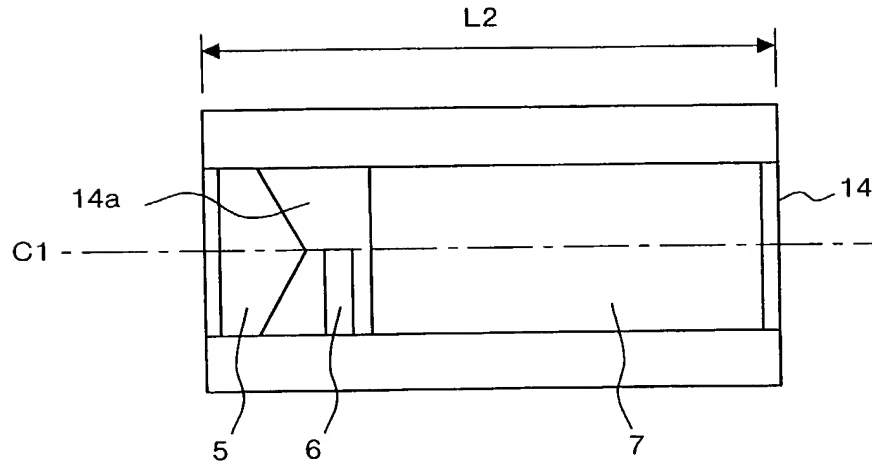


FIG.4B

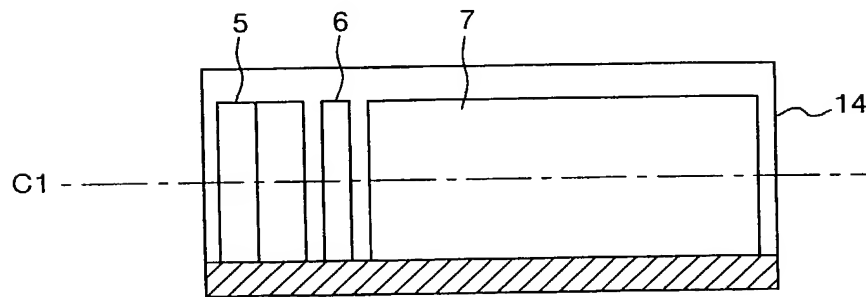
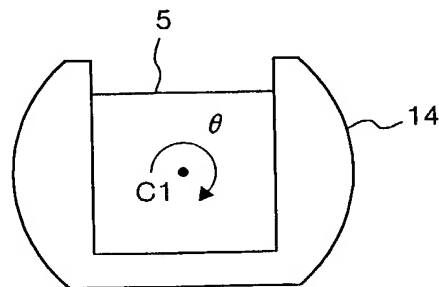


FIG.4C



5/18

FIG.5A

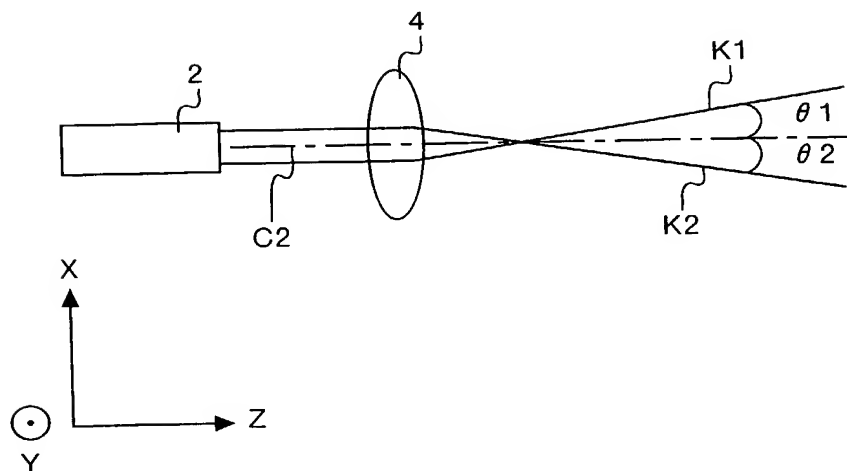


FIG.5B

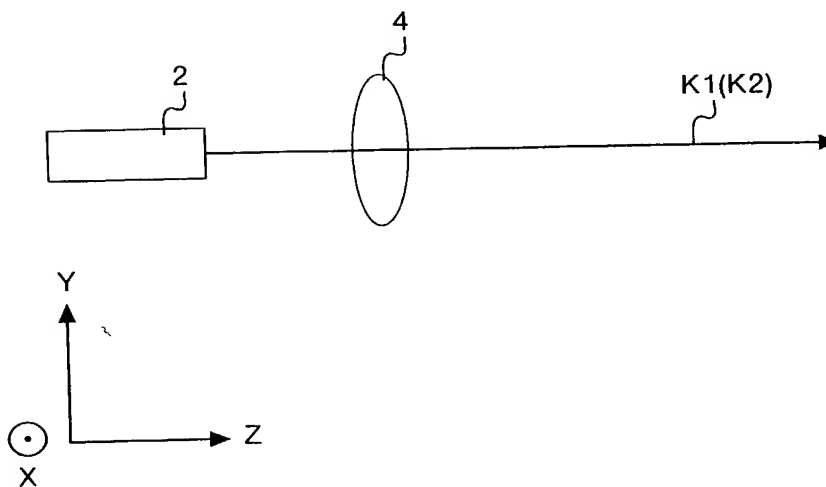


FIG.6A

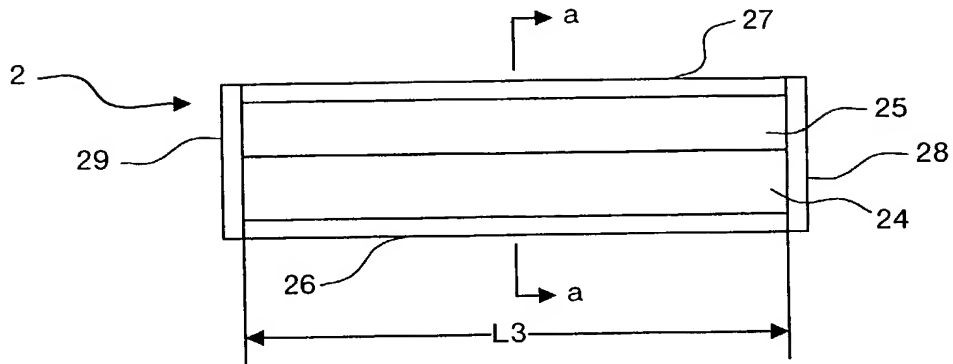
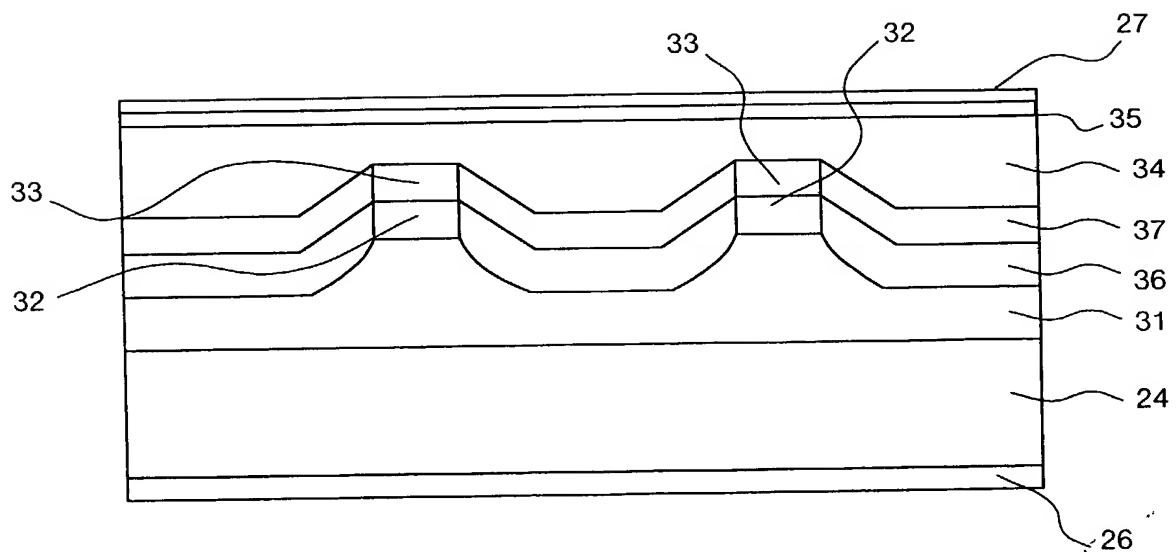
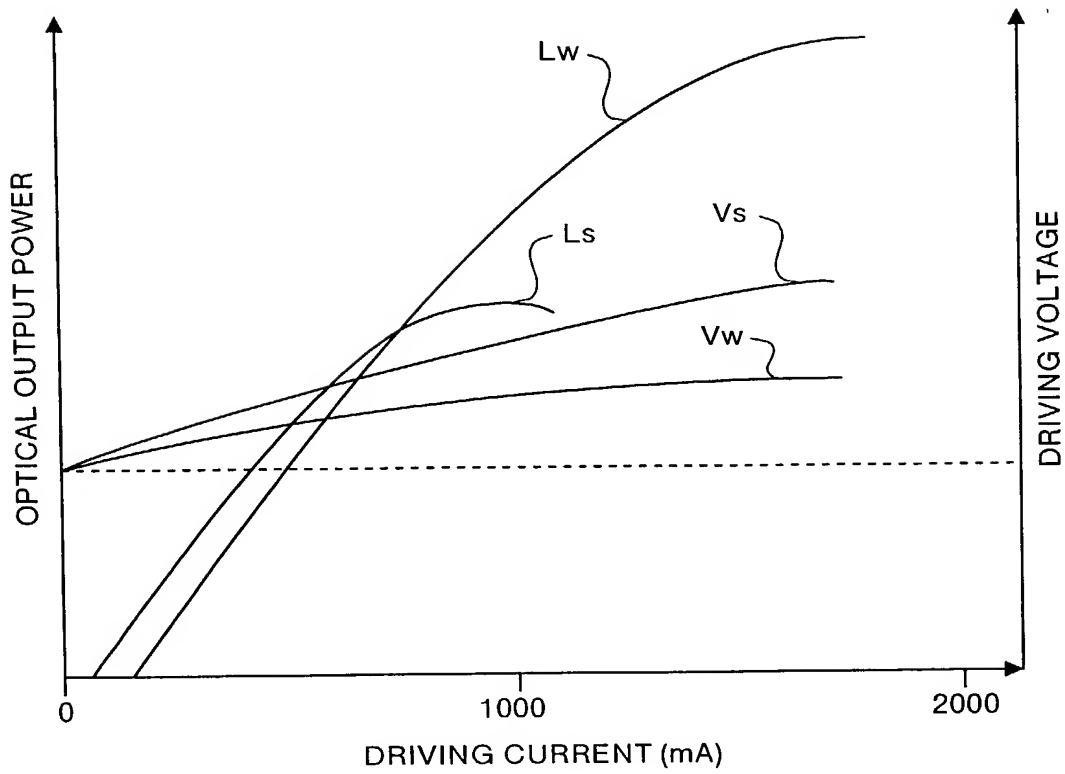


FIG.6B



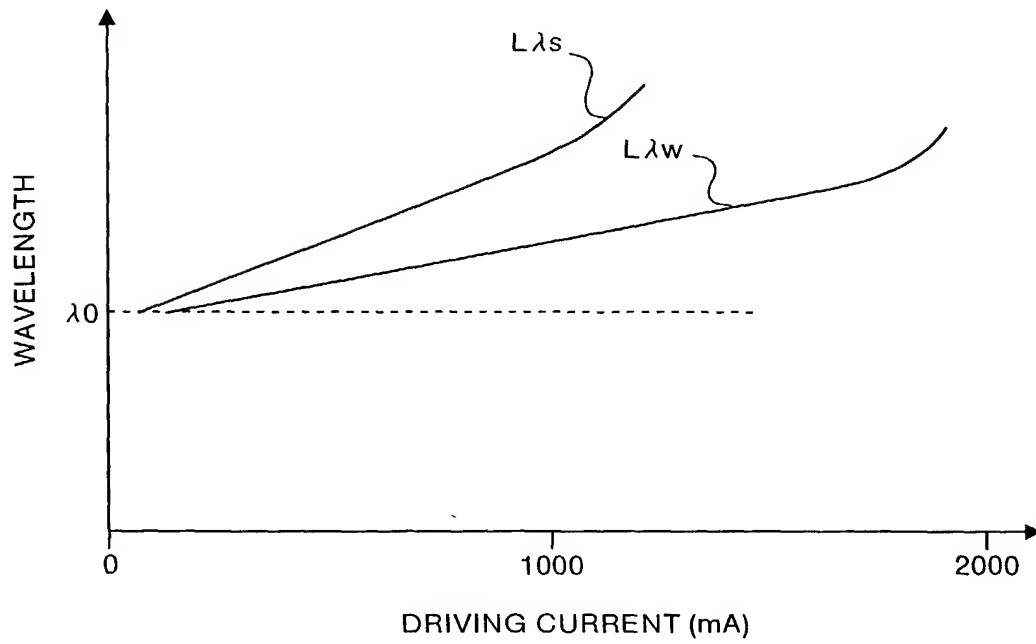
7/18

FIG.7



8/18

FIG.8





9/18

FIG.9

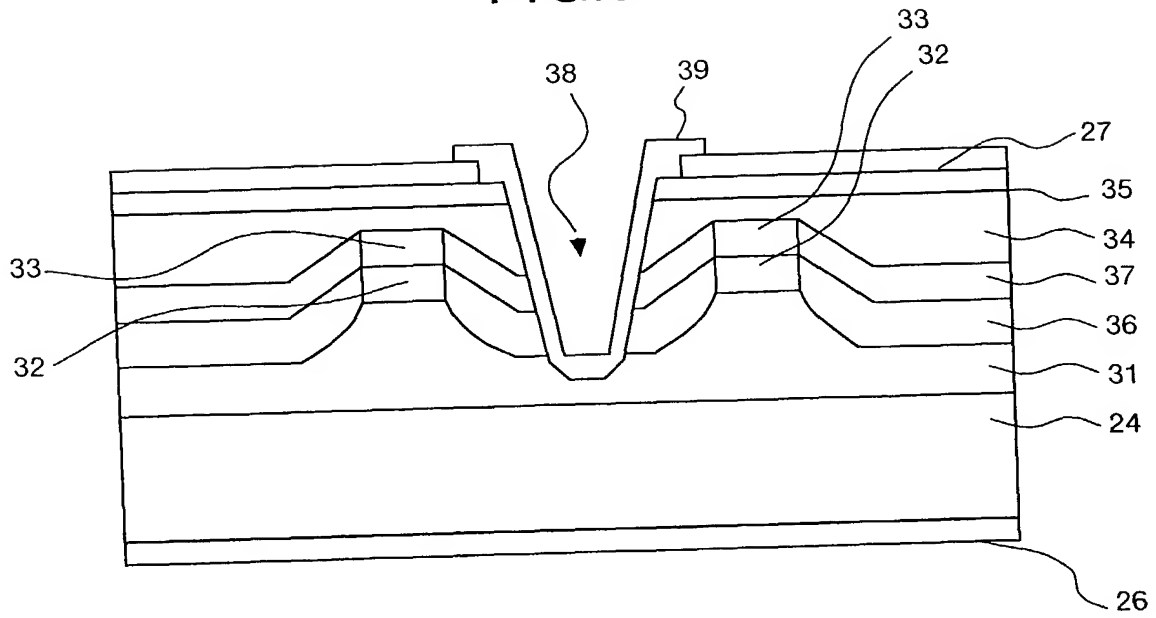
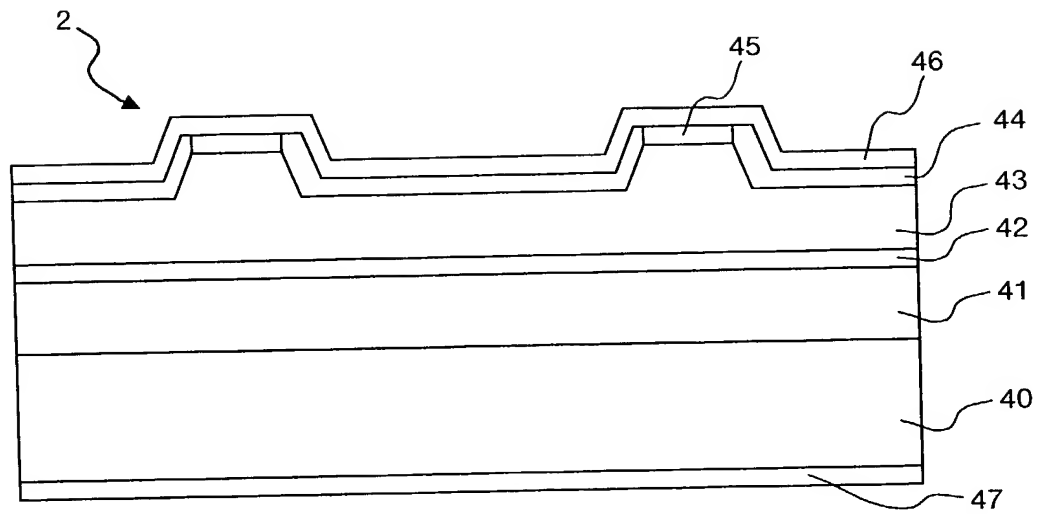


FIG.10



11/18

FIG.11

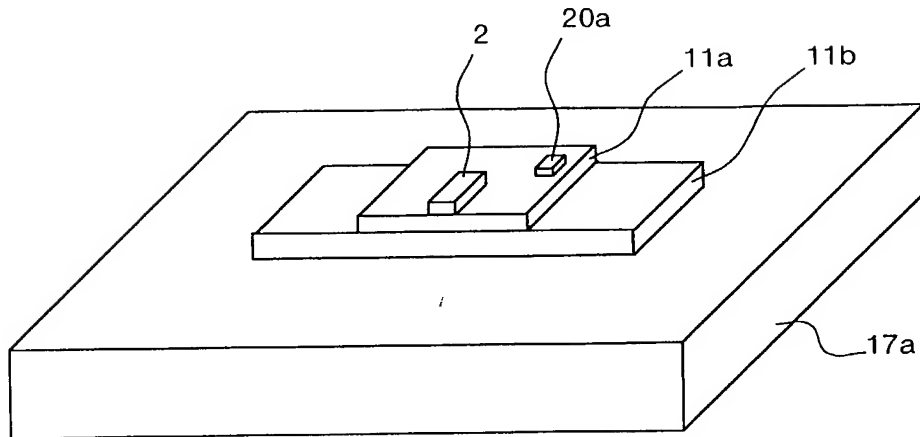


FIG.12

		A	B
UPPER HEAT SINK		CVD DIAMOND	AlN
LOWER HEAT SINK		AlN	AlN
HEAT OUTPUT [W]	LEFT ACTIVE LAYER	2.5	2.5
	RIGHT ACTIVE LAYER	2.5	2.5
TEMPERATURE [°C]	LEFT ACTIVE LAYER	37.96	49.53
	RIGHT ACTIVE LAYER	37.96	49.53
	UPPER MOUNT	26.76	26.77

12/18

FIG.13

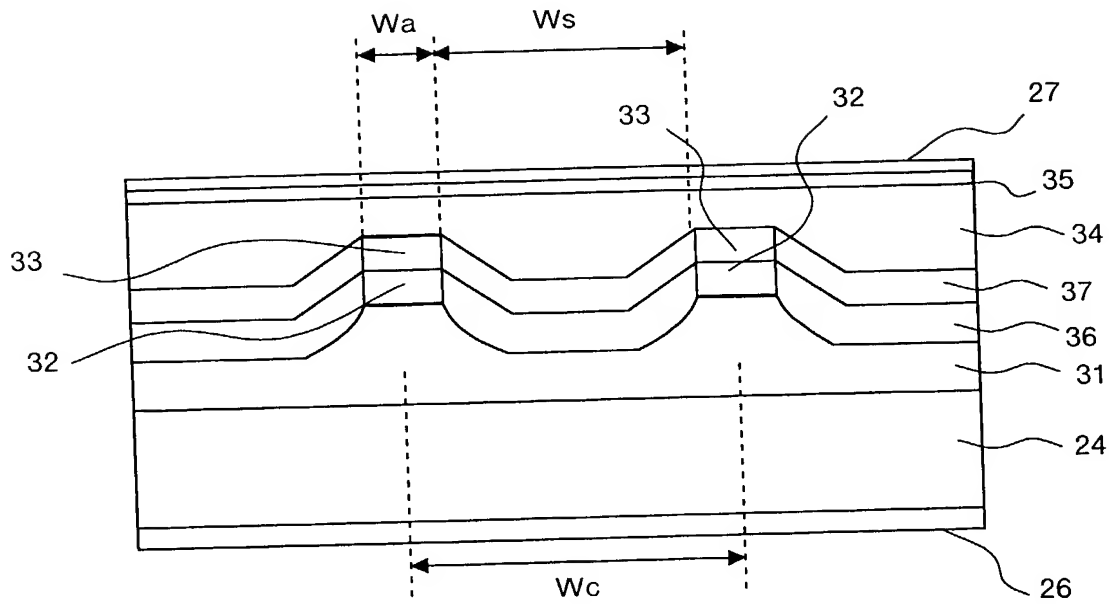
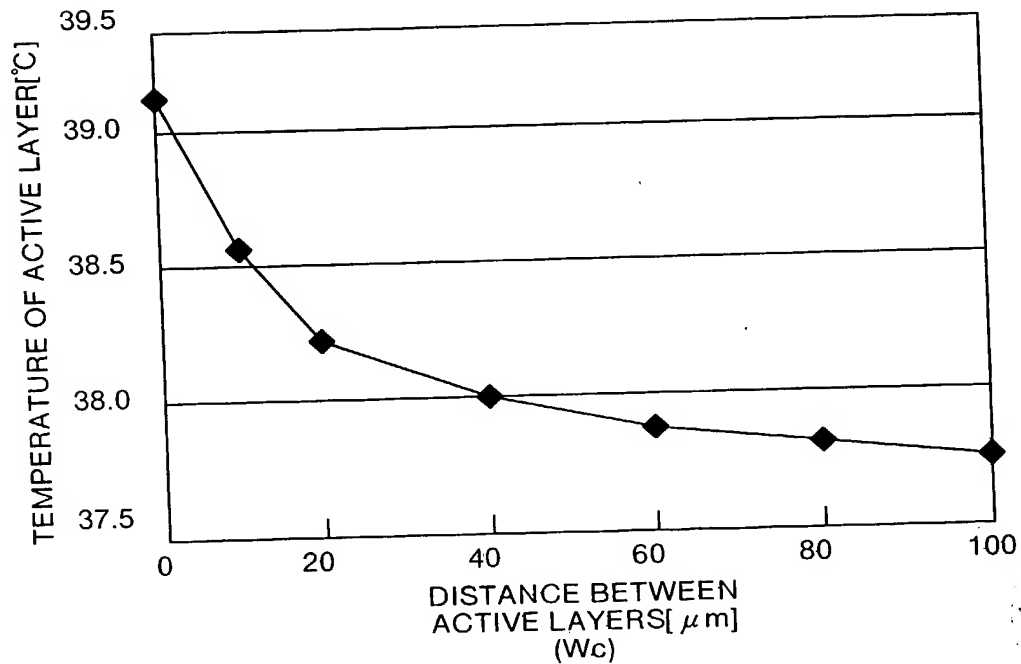
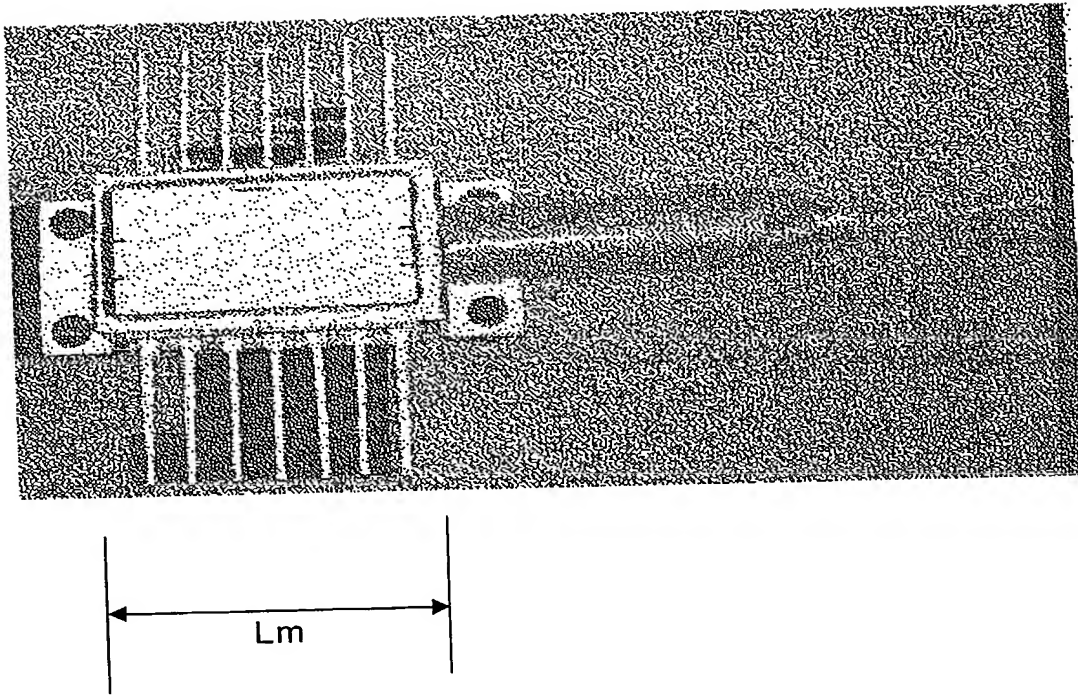


FIG.14



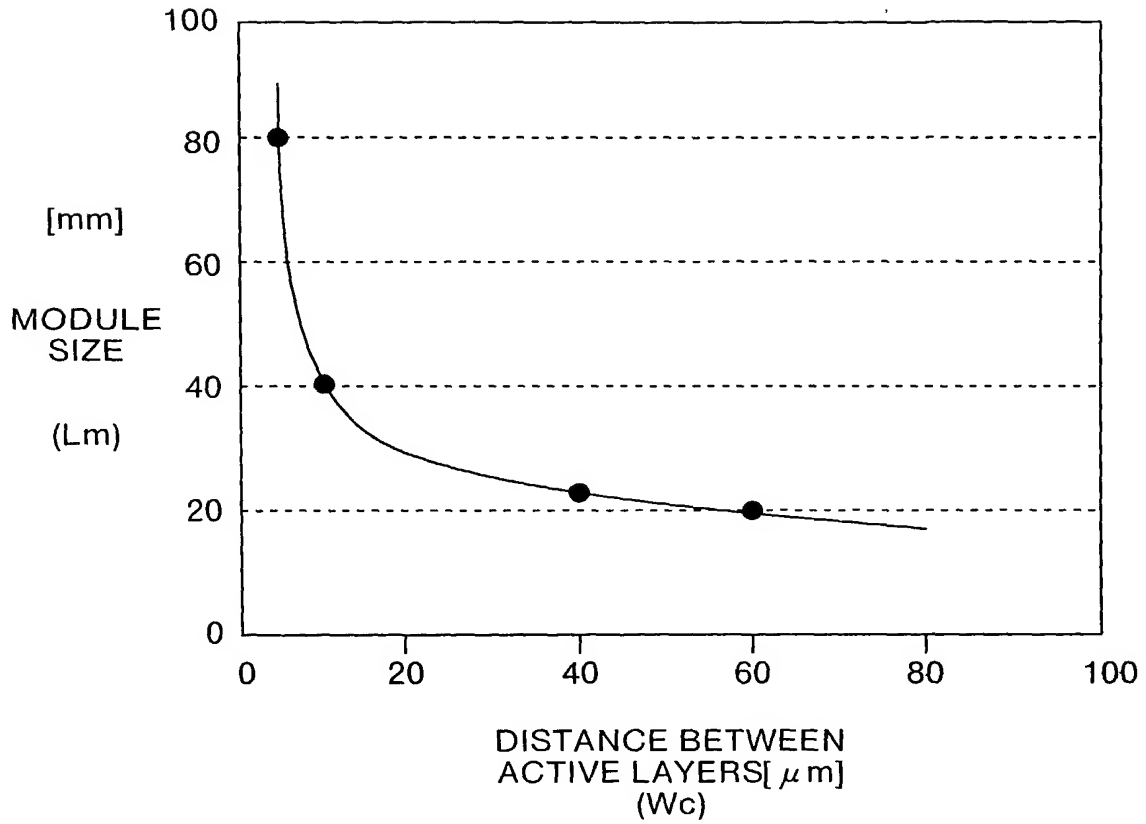
13/18

FIG.15



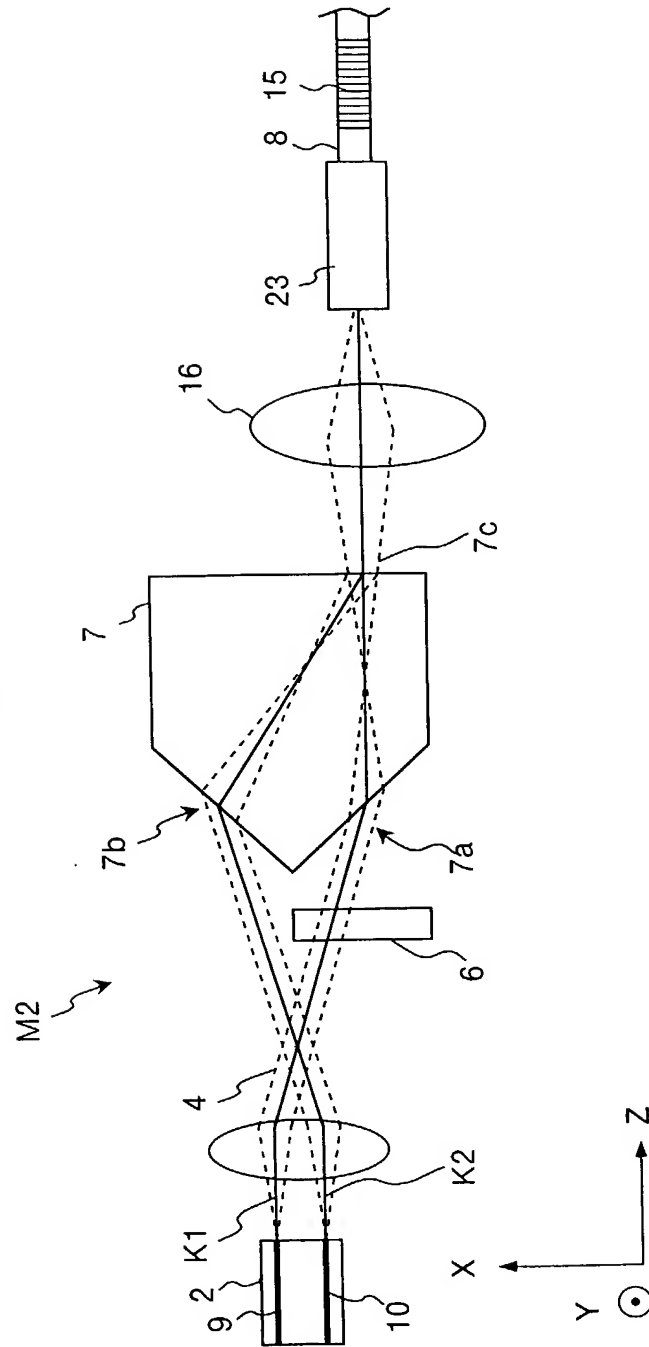
10/015,627  
KANEMARU, et al  
217494US8  
SHEET 13 OF 18

FIG.16



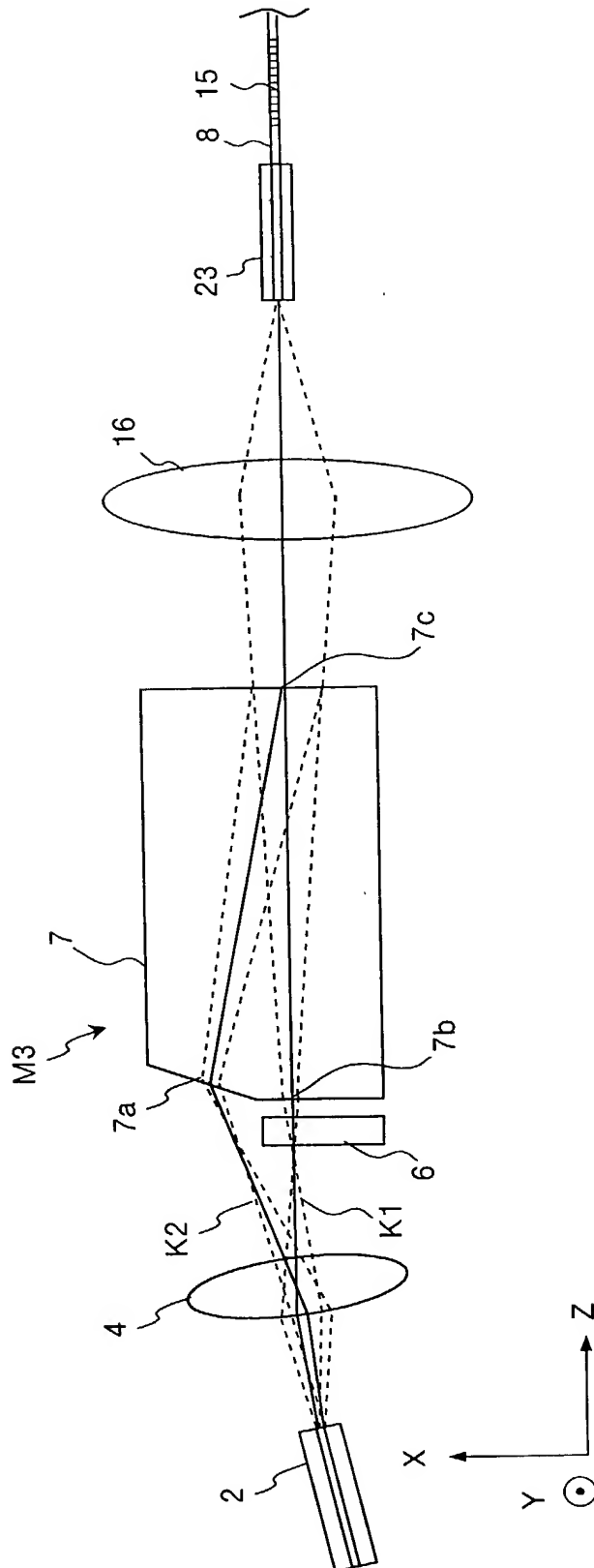
15/18

FIG.17



16/18

FIG.18





17/18

FIG.19

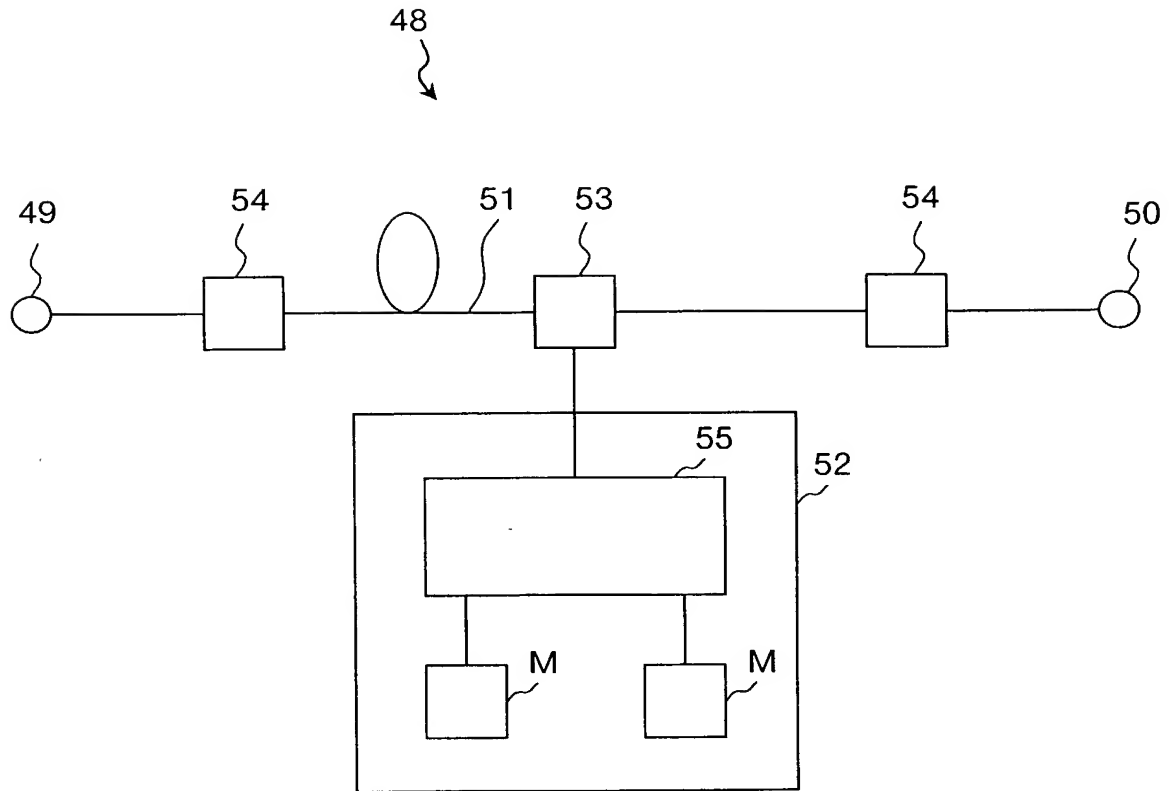


FIG.20

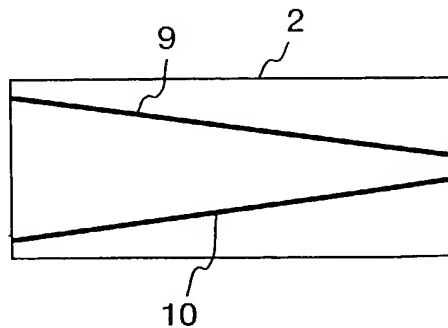


FIG.21

